

DESIGN OF ANALOG SIGNAL PROCESSING INTEGRATED CIRCUIT FOR MULTI-CHANNEL BIOMEDICAL STRAIN MEASUREMENT INSTRUMENT

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Abstract: An analog signal processing integrated circuit for micro-cantilever array is designed for strain measurement in biomedical applications. The chip includes an analog multiplexer, an instrumentation amplifier, a sample and hold circuit, an on-chip voltage and current reference, a successive approximation register analog-to-digital converter and a digital control unit. The 8-bit ADC attains 45.4 dB signal-to-noise-and-distortion ratio and 56.4 dB spurious-free-dynamic-range while operating at 772 KHz. The chip occupies an area of 1.54 mm² and consumes 17.8 mW power with a single 3.3 V supply. The chip has been fabricated in a 0.35µm 2-poly 4-metal CMOS process technology.

1 INTRODUCTION

The use of prosthetic joint implants to treat patients with severe osteoarthritis and other joint degenerative diseases began in the early 70s. During the knee joint implant surgery, surgeons need to perform accurate resections depending on various instruments such as spacer block, tensioner and tram adapter. These instruments provide valuable information about the gap shape and size during the bone resection process. However, the feedback of instrument such as the spacer block is qualitative and the degree of tightness of the ligaments is inaccessible.

A new space blocker, shown in figure 1, is designed by fully taking advantage of the sensors, the ASIC and the telemetry technology. The sensors and chips are on the surface with a battery inside the spacer block, and the antenna is also designed to fit in the handle. The surface of the instrument was encapsulated by epoxy with fully FDA compliance.

In this paper, we mainly present the design of an analog signal processing IC for biomedical strain

measurement system. In Section 2, we briefly introduce the system design and then present the circuit design in detail in Section 3. The measurement results are given in Section 4, followed by a summary in Section 5.

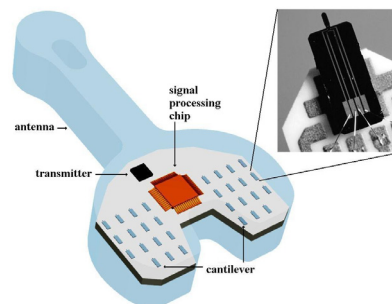


Figure 1: 3-D model of spacer block with embedded chip and sensor array.

2 SYSTEM OVERVIEW

The system block diagram is shown in figure 2. The system can be partitioned into three parts based on

their functions. The first part is the sensor array. There are 30 strain-sensing micro-cantilevers distributed evenly on the two sides of the biomedical instrument top plate. The Wheatstone bridge configured sensors convert the physical strain to a resistance change and then to voltage signal under DC excitation. The middle part shown in figure 2 includes two chips, one chip for signal processing and another one for signal transmitting. The signal-processing chip amplifies the signal coming from the sensors and digitizes the analog signal to digital domain. The transmitter chip sends out the signal using ASK modulation with 335MHz carrier frequency. The receiver part receives and recovers the data remotely. Furthermore, the data will be post-processed by software and shown graphically on the display.

In this paper, the scope mainly focuses on the design and implementation of the signal processing integrated circuit.

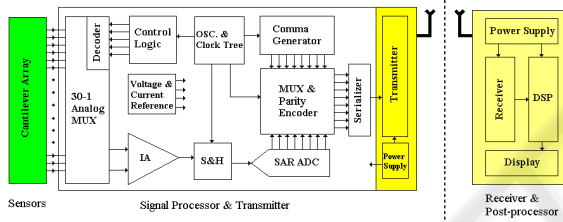


Figure 2: Sensor array signal processing system block diagram.

3 CIRCUIT IMPLEMENTATION

Instrumentation Amplifier. The Instrumentation Amplifier (IA) amplifies the difference signal between the two input terminals and rejects the common mode signals on both inputs (Kitchin and Counts, 2000). Unlike normal opamp, the feedback of IA uses an internal resistance network but the gain is set by an external resistor.

The external gain setting resistor provides maximum design flexibility for the system designer to accommodate the input signal level. The gain can be set using the following equation

$$A_V = 1 + \frac{2R}{R_g} \quad (1)$$

where, R is internal resistor and R_g is off chip gain setting resistor.

A classical 3 opamps configuration is chosen and an additional opamp provides variable output DC level to accommodate the following stage circuit.

Voltage and Current Reference. Both the ADC and the DAC in the system need either the voltage or the current reference. Bandgap voltage reference is selected for its extraordinary performance of process, power supply and temperature variation independence (Meyer and Gray, 1993, Brokaw, 1974). The reference is generated by adding a negative temperature coefficient (TC) voltage and a weighted positive TC voltage. Hence, a zero TC can be achieved by adjusting the value of R_2 and R_1 based on the following equation

$$V_{BG} = V_{be} + \frac{R_2}{R_1} V_T \ln k \quad (2)$$

where, V_{be} is the base-emitter junction voltage, V_T is thermal voltage and k is the geometry ratio of Q_1 and Q_2 . The bandgap reference circuit shown in figure 3 has two operation points. To guarantee the circuit always works at the right point, a startup circuit is also included.

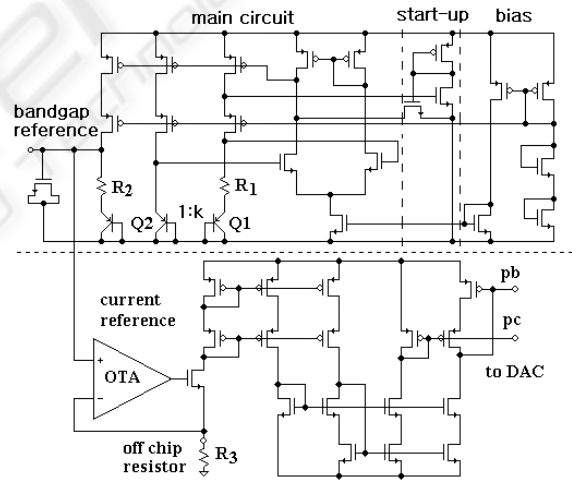


Figure 3: Voltage and Current Reference Schematic.

The current reference for the current-steering DAC cannot be fully generated on-chip due to the lack of a high precision absolute value resistor. With the aid of a low TC and high precision external resistor, and the bandgap voltage reference, an accurate current reference can be obtained. The current reference circuit is shown in the lower part of figure 3.

Sample and Hold. In order to relax the dynamic requirements for the ADC, a sample and hold circuit is inserted between the amplifier and the ADC (Waltari and Halonen, 2002). The sample and hold grabs the fast changing signal and stores it in the sampling capacitor C_s . In the meantime, the thermal noise is also trapped into the capacitor during the turning off of the switch. For an 8-bit ADC, the minimum required sampling capacitor C_s can be calculated by the following equation

$$C_s = n_f \frac{k_B T}{V_n^2} \quad (3)$$

where, k_B is Boltzmann constant, T is absolute temperature, V_n^2 is quantization noise power, and the coefficient n_f models the noise from the amplifier and has a value between 0~1. In (3), we assume that the quantization noise power is equal to the thermal noise power.

The settling error for linear one pole settling is expressed as

$$\varepsilon_r = e^{-\frac{\omega_{-3dB}}{2f_s}} = e^{-\frac{1}{2f_s R_S C_s}} \quad (4)$$

where, f_s is sampling frequency and R_S is the equivalent on-resistance of sampling switch. The maximum allowed settling error for 8-bit ADC is 0.39%. Then the equivalent resistance for the switch can be calculated by

$$R_S = \frac{1}{2} \frac{1}{f_s C_s \ln \frac{1}{\varepsilon_r}} \quad (5)$$

where, ε_r is settling error. Once we know the minimum equivalent on-resistance of the switch, the switch size can be determined by the transistor parameters.

SAR ADC. The Successive Approximation Register (SAR) ADC (Scott et al., 2003) is selected as the data conversion unit for several reasons. First, the SAR ADC is suitable for moderate speed and moderate resolution data conversion. Also, the SAR ADC is extremely power and area efficient. The SAR ADC shown in figure 4 has three parts: comparator, SAR logic (Anderson, 1972) and DAC. The conversion mechanism behind the SAR ADC is similar to binary search algorithm. First, the DAC MSB is set to 1 while all other bits are set to 0, then converted to analog domain and compared with the stored input signal. Then the SAR logic will keep or

reset the MSB signal based the comparison result. The procedure is iterated until the LSB is resolved. Apparently, the conversion time is 8 periods for an 8-bit ADC plus 1 period for sampling. The timing and conversion procedure is shown in figure 4b.

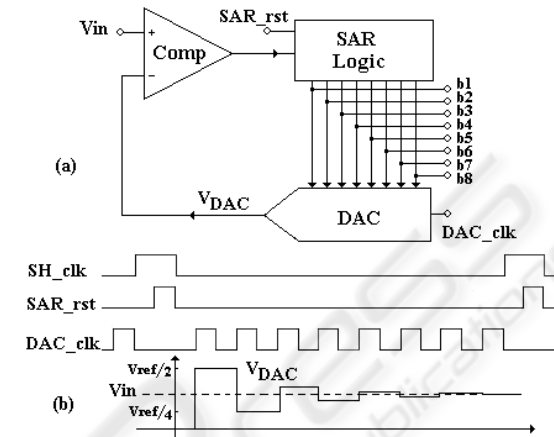


Figure 4: SAR ADC block and timing diagram.

4 EXPERIMENTAL RESULTS

Figure 5 shows the signal process chip micrograph. The core die area (excluding the pad and ESD circuit) is about 1.54 mm².

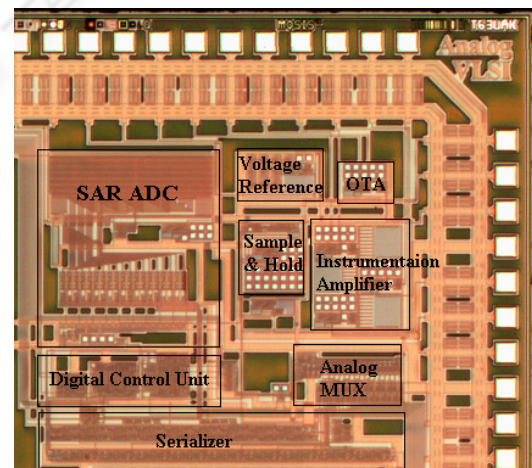


Figure 5: Chip prototype micrograph.

The voltage gain frequency response of the IA is shown in figure 6 for three different external gain setting resistors. The unity gain bandwidth for different voltage gain is almost fixed and has a value about 2.5 MHz.

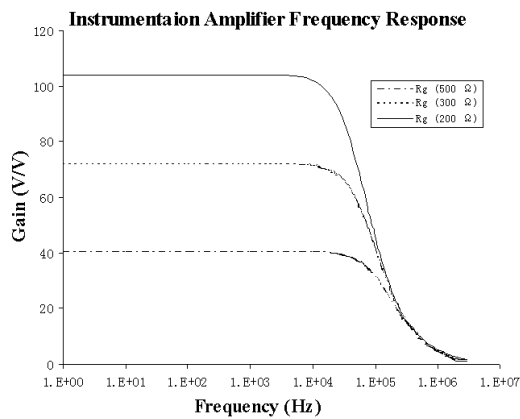


Figure 6: Voltage gain frequency response of instrumentation amplifier.

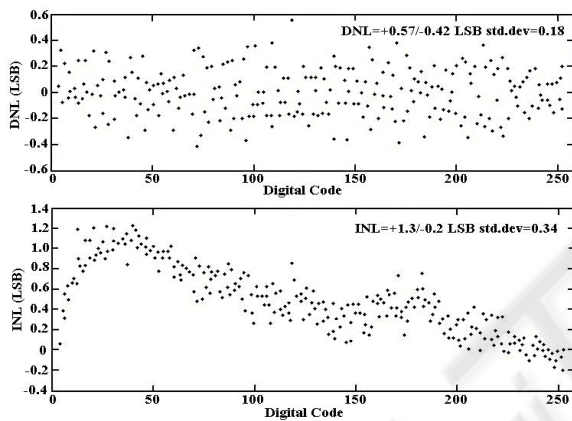


Figure 7: Integral and differential nonlinearity of ADC.

Table 1: Prototype chip performance summary.

	Parameter	Value
ADC	Resolution	8 bit
	ENOB	7.24 bit
	SNDR	45.4 dB
	SFDR	56.4 dB
	Conversion Rate	772 KHz
	DNL	+0.57/-0.42 LSB
	INL	+1.3/-0.2 LSB
	Area	0.43 mm ²
	Power	17.8 mW
Instrumentation Amplifier	Voltage Gain	20~200 V/V
	Unity Gain Bandwidth	2.5 MHz
Total	Area	1.54 mm ²
	Power	17.8 mW

The DNL and INL of the SAR ADC are obtained by histogram testing (Plassche, 2003) and are shown

in figure 7. The DNL is 0.57/-0.42 LSB and INL is 1.3/-0.2 LSB with zero missing code. Parts of the test results are summarized in table 1.

5 CONCLUSIONS

The prototype chip presented here was fabricated in a 0.35 μm 2-poly 4-metal CMOS process. The operating voltage is 3.3 V and the chip can also work for the voltage range of 2.6 V ~ 4 V. The area of the chip (core area) is 1.54 mm², and consumes 5.4 mA current. The measurement results of the signal processing chip verify the design concept and meet the specifications for the biomedical instrument system. A wireless strain measurement instrument is being developed based on this chip design.

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